MS-450 Wave soldering system specifications

Specifications	MS-450	Remarks
Dimension(L×W×H mm)	4430X1620X1710	
Weight	Approx:2300kg	
Power Supply	220V 50/60HZ 34KW	
Startup Power	26kw	
Power Consumption	approx.14kw	
Control System	IBM PC PLC	
Spray System		
spray work mode	Nozzle spray	
Spray pressure	0.25MPa~0.4MPa	
Flux flow arrange	10-100ml/min	
Autofill flux	S	
Exhaust	up-down exhaust	
Exhaust ducting diameter	200	
Exhaust capacity	25M^3/min	
Preheating System		
Preheating mode	Hot air/IR tube	option:IR tube
Preheating zone number	3	
Preheating lenghth(mm)	1800	
Preheating temperature(C)	room temperature 250	
Warm-up time(min)	approx.15min setting:150	
Control mode	PID+SSR	
Blower motor	S	
Conveyor System		
PCB width (L×W)(mm)	Min:80×60 ; Max:500×450	
Conveyor speed (mm/min)	0-2000	
Conveyor direction	L R	option: R L
Conveyor height(mm)	750±20	option:900±20
Available component height	top:120mm,bottom:15mm	
Conveyor Speed Control	inverter closed loop	
Finger	Dual chain and quick change	
Conveyor width control	Motor	
Conveyor angle	4° 7°	
Soldering System		
Solder pot style	Mechanism/Electromagnetic	Option:Electromagnetic
Solder pot material	SUS316L/full titanium	
Wave height adjust	inverter	
Heater power	220VAC 12KW/10KW	
Solder pot temperature (C)	300	
Solder pot capacity	1,500 lbs	
Wave drive power	1/2HPX2 3P220V/2KW 220V	
Solder pot warm-up time	approx.240min(setting:250)	
Temperature control mode	PID+SSR	
Cooling System		
cooling method	Forced air/ air chiller	option:Air chiller
Others		
Finger cleaning system	brush	In front and back
Return trip lifting	S	
Option		
Center support	O	
J-sonic Ultrasonic spray	O	
Top heating	O	
UPS protect	O	
Nitrogen device	O	
Feeder knife	O	